

WAFER CLEANING EQUIPMENT, WAFER CHUCK, AND WAFER CLEANING METHOD

ABSTRACT

The present disclosure provides a wafer chuck in semiconductor cleaning equipment, including a chuck base, a jetting assembly arranged on the chuck base, and a plurality of wafer lifting shafts arranged on the chuck base. The chuck base includes a carrier surface for supporting the wafer. The gas outlet of the jetting assembly is located in the center area of the carrier surface and configured to jet gas between the carrier surface and the wafer. The plurality of wafer lifting shafts are distributed around the gas outlet of the jetting assembly along the circumference of the carrier surface. Each wafer lifting shaft of the plurality of wafer lifting shafts is movable relative to the chuck base, and each wafer lifting shaft includes an inclined platform. The inclined platform includes an inclined extension surface. The inclined extension surface is configured to carry the wafer at the edge of the wafer and is configured to cause the wafer to move to different height positions along the inclined extension surface when the wafer lifting shaft moves relative to the chuck base. In the present disclosure, the wafer height can be accurately positioned, and the wafer cleaning efficiency can be improved. The present disclosure further provides wafer cleaning equipment and a wafer cleaning method.

FIG. 2B